

Form PTO-1449

Attorney Docket No.
62020-1290Serial No.
10/699,287

INFORMATION DISCLOSURE CITATION

Applicant
Mule', et al.Filing Date
10/31/03Group
TBD

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
/M.D./	A	4,380,365	4/19/83	Gross	350	96.18	5/23/79
	B	5,046,800	9/10/91	Blyler, Jr., et al.	385	131	10/9/90
	C	5,130,356	7/14/92	Feuerherd, et al.	524	96	2/1/90
	D	5,302,656	4/12/94	Kohara, et al.	524	579	4/10/91
	E	5,359,208	10/25/94	Katsuki, et al.	257	82	2/26/93
	F	5,454,196	7/18/95	Ohkawa, et al.	522	100	7/1/94
	G	5,462,995	10/31/95	Hosaka, et al.	525	332.1	6/9/92
	H	5,581,414	12/3/96	Snyder	359	819	2/22/93
	I	5,896,479	4/20/99	Vladic	385	59	4/9/97
	J	6,022,498	2/8/00	Buazza, et al.	264	1.38	4/19/96
/M.D./	K	6,039,897	3/21/00	Lochhead, et al.	264	1.24	8/28/97

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation
						Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

/M.D./	L	Chen, et al.; Fully Embedded Board-Level Guided-Wave Optoelectronic Interconnects; June, 2000; Proceedings of IEEE, Vol. 88, No. 6; pp 780-793
/M.D./	M	Wiesmann, et al.; Singlemode Polymer Waveguides for Optical Backplanes; December 5, 1996; Electronics Letters, Vol. 32, No. 25; pp 2329-2330
/M.D./	N	Barry, et al.; Highly Efficient Coupling Between Single-Mode Fiber and Polymer Optical Waveguides; August, 1997; IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part B, Vol. 20, No. 3; pp 225-228
/M.D./	O	Lee, et al.; Fabrication of Polymeric Large-Core Waveguides for Optical Interconnects Using a Rubber Molding Process; January, 2000; IEEE Photonics Technology Letters, Vol. 12, No. 1; pp 62-64
/M.D./	P	Schneider, et al.; Electro-Optical Printed Circuit Board (EOPCB); 2000 Electronic Components and Technology Conference; pp 749-753
/M.D./	Q	Mederer, et al.; 3Gb/s Data Transmission With GaAs VCSELs Over PCB Integrated Polymer Waveguides; September, 2001; IEEE Photonics Technology Letters, Vol. 13, No. 9; pp 1032-1034

* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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/M.D./	R	6,156,394	12/5/00	Schultz Yamasaki, et al.	427	536	4/17/98
	S	6,206,673	3/27/01	Lipscomb, et al.	425	174.4	5/30/95
	T	6,253,004	6/26/01	Lee, et al.	385	31	7/9/99
	U	6,259,567	7/10/01	Brown, et al.	359	668	11/23/98
	V	6,262,414	7/17/01	Mitsubishi	250	216	7/27/99
	W	6,272,275	8/7/01	Cortright, et al.	385	129	6/25/99
	X	6,281,508	8/28/01	Lee, et al.	250	396	2/8/99
	Y	6,432,328	8/13/02	Hamanaka, et al.	264	1.36	1/10/01
/M.D./	Z	6,500,603	12/31/02	Shioda	430	321	11/9/00
	AA						
	BB						

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							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

/M.D./	CC	Schröder, et al.; Polymer Optical Interconnects for PCB; 2001; Session 13: Photonic Polymers II; pp 337-343						
/M.D./	DD	Glukh, et al.; High performance Polymeric Materials for Waveguide Applications; August, 2000; SPIE - The International Society for Optical Engineering, Invar, Nonlinear, and Power Limiting Organics, San Diego, Volume 4106; pp 1-11						
/M.D./	EE	Liu, et al.; Plastic VCSEL Array Packaging and High Density Polymer Waveguides for Board and Backplane Optical Interconnect; 1998; Electronic Components and Technology Conference; pp 999-1005						
/M.D./	FF	Bakir, et al.; Sea of Dual Mode Polymer Pillar I/O Interconnections for Gigascale Integration; 2003; IEEE International Solid State Circuits Conference; 8 pages						
/M.D./	GG	Beuret, et al.; Microfabrication of 3D Multidirectional Inclined Structure by UV lithography and Electroplating; Micro Electro Mechanical Systems, 1994, MEMS'94, Proceedings, IEEE Workshop on January 25-28, 1994; pp 81-85						
/M.D./	HH	Wang, et al.; Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump; Electronic Components and Technology Conference, 2001, Proceedings, 51st, 29 May-1, June 2001; pp 945-949						

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	II						
	JJ						
	KK						

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							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

/M.D./	LL	Bakir, et al.; Sea of Polymer Pillars: Dual-Mode Electrical Optical Input/Output Interconnections; in Proc. of Int. Interconnect Technology Conference; pp. 77-79; 2003
/M.D./	MM	Bakir, et al.; Sea of Polymer Pillars: Compliant Wafer-Level Electrical-Optical Chip I/O Interconnections; IEEE Photonics Technology Letters, Vol. 15, No. 11, November 2003; pp 1567-1569
/M.D./	NN	Bakir, et al.; Optical Transmission of Polymer Pillars for Chip I/O Optical Interconnections; IEEE Photonics Technology Letters, Vol. 16, No. 1, January 2004; pp 117-119
/M.D./	OO	Chandrasekhar, et al.; Modeling and Characterization of the Polymer Stud Grid Array (PSGA) Package: Electrical, Thermal and Thermo-Mechanical Qualification; IEEE Transactions on Electronics Packaging Manufacturing, Vol. 26, No. 1, January 2003; pp 54-67

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